

KEMET Part Number: C0805X333F3GECTU
(C0805X333F3GEC7800)

ESD SMD Comm COG, Ceramic, 0.033 uF, 1%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805



Dimensions

| Chip Size | 0805 |
|-----------|------------------|
| L | 2mm +/-0.3mm |
| W | 1.25mm +/-0.3mm |
| T | 1.25mm +/-0.15mm |
| S | 0.75mm MIN |
| B | 0.5mm +/-0.25mm |

Packaging Specifications

| | |
|----------------------------|--------------------------|
| Packaging: | T&R, 180mm, Plastic Tape |
| Packaging Quantity: | 2500 |

General Information

| | |
|--------------------------|--|
| Series: | ESD SMD Comm COG |
| Style: | SMD Chip |
| Description: | SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I |
| Features: | Temperature Stable, Low ESR, Class I |
| RoHS: | Yes |
| Termination: | Flexible Termination |
| Marking: | No |
| AEC-Q200: | No |
| Component Weight: | 14 mg |
| Shelf Life: | 78 Weeks |
| MSL: | 1 |

Specifications

| | |
|--|------------------------|
| Capacitance: | 0.033 uF |
| Measurement Condition: | 1 kHz 1.0Vrms |
| Capacitance Tolerance: | 1% |
| Voltage DC: | 25 VDC |
| ESD Level per AEC-Q200: | 25,000 V ESD Level |
| Dielectric Withstanding Voltage: | 62.5 VDC |
| Temperature Range: | -55/+125°C |
| Temperature Coefficient: | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC): | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor: | 0.1% 1 kHz 1.0Vrms |
| Aging Rate: | 0% Loss/Decade Hour |
| Insulation Resistance: | 30.303 GOhms |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)